

**APPARATUS AND METHOD FOR
REPAIRING ELECTRONIC PACKAGES**

ABSTRACT

A multi chip module substrate arranged with repair vias and repair lines

- 5 extending between repair vias of the chip sites of the module by which repairs can be
- effected to overcome defects in the module circuits and a method for effecting the repairs
- of defects in the circuits of this module. A defect can occur in any one of a first signal
- via, a second signal via, and a circuit line extending between and intended to electrically
- connect the first signal via and the second signal via. After a defective circuit is
- 10 identified, the signal vias of the circuit are isolated. Then, the first signal via of the
- defective circuit is electrically connected to that repair via of the chip site having the first
- signal via that is connected to that repair via of the chip site having the second signal via
- and the second signal via of the defective circuit is electrically connected to that repair via
- of the chip site having the second signal via that is connected to that repair via of the chip
- 15 site having the first signal via.